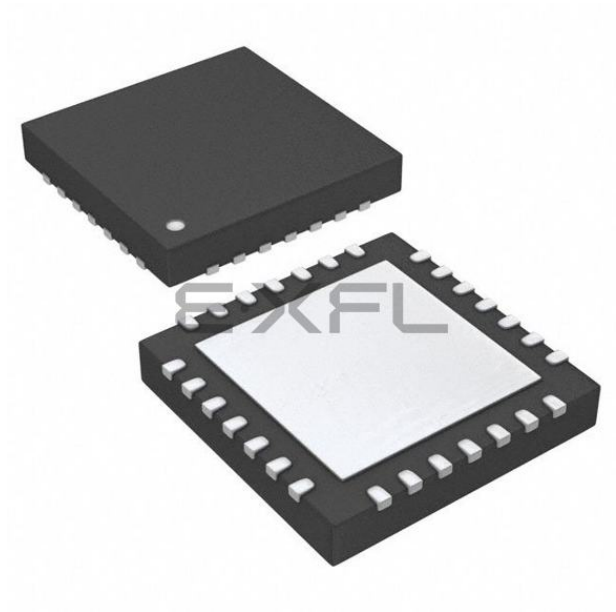

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, I²S, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 10x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx170f256b-i-ml

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number[1]				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
USBID	11[3]	14[3]	15[3]	41[3]	I	ST	USB OTG ID detect
CTED1	27	2	33	19	I	ST	CTMU External Edge Input
CTED2	28	3	34	20	I	ST	
CTED3	13	16	17	43	I	ST	
CTED4	15	18	19	1	I	ST	
CTED5	22	25	28	14	I	ST	
CTED6	23	26	29	15	I	ST	
CTED7	—	—	20	5	I	ST	
CTED8	—	—	—	13	I	ST	
CTED9	9	12	10	34	I	ST	
CTED10	14	17	18	44	I	ST	
CTED11	18	21	24	8	I	ST	
CTED12	2	5	36	22	I	ST	
CTED13	3	6	1	23	I	ST	
CTPLS	21	24	27	11	O	—	CTMU Pulse Output
PGED1	1	4	35	21	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 1
PGEC1	2	5	36	22	I	ST	Clock input pin for Programming/Debugging Communication Channel 1
PGED2	18	21	24	8	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 2
PGEC2	19	22	25	9	I	ST	Clock input pin for Programming/Debugging Communication Channel 2
PGED3	11[2]	14[2]	15[2]	41[2]	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 3
	27[3]	2[3]	33[3]	19[3]			
PGEC3	12[2]	15[2]	16[2]	42[2]	I	ST	Clock input pin for Programming/ Debugging Communication Channel 3
	28[3]	3[3]	34[3]	20[3]			
PGED4	—	—	3	12	I/O	ST	Data I/O pin for Programming/Debugging Communication Channel 4
PGEC4	—	—	4	13	I	ST	Clock input pin for Programming/ Debugging Communication Channel 4

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number(1)				Pin Type	Buffer Type	Description
	28-pin QFN	28-pin SSOP/ SPDIP/ SOIC	36-pin VTLA	44-pin QFN/ TQFP/ VTLA			
$\overline{MCLR}$	26	1	32	18	I/P	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	25	28	31	17	P	—	Positive supply for analog modules. This pin must be connected at all times.
AVSS	24	27	30	16	P	—	Ground reference for analog modules
VDD	10	13	5, 13, 14, 23	28, 40	P	—	Positive supply for peripheral logic and I/O pins
VCAP	17	20	22	7	P	—	CPU logic filter capacitor connection
VSS	5, 16	8, 19	6, 12, 21	6, 29, 39	P	—	Ground reference for logic and I/O pins. This pin must be connected at all times.
VREF+	27	2	33	19	I	Analog	Analog voltage reference (high) input
VREF-	28	3	34	20	I	Analog	Analog voltage reference (low) input

Legend: CMOS = CMOS compatible input or output; Analog = Analog input; P = Power
ST = Schmitt Trigger input with CMOS levels; O = Output; I = Input
TTL = TTL input buffer; PPS = Peripheral Pin Select; — = N/A

Note 1: Pin numbers are provided for reference only. See the **"Pin Diagrams"** section for device pin availability.

2: Pin number for PIC32MX1XX devices only.

3: Pin number for PIC32MX2XX devices only.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MCUs

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the documents listed in the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

2.1 Basic Connection Requirements

Getting started with the PIC32MX1XX/2XX 28/36/44-pin Family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins (see **2.2 "Decoupling Capacitors"**)
- All AVDD and AVSS pins, even if the ADC module is not used (see **2.2 "Decoupling Capacitors"**)
- VCAP pin (see **2.3 "Capacitor on Internal Voltage Regulator (VCAP)"**)
- $\overline{\text{MCLR}}$ pin (see **2.4 "Master Clear (MCLR) Pin"**)
- PGECx/PGEDx pins, used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes (see **2.5 "ICSP Pins"**)
- OSC1 and OSC2 pins, when external oscillator source is used (see **2.7 "External Oscillator Pins"**)

The following pins may be required:

- VREF+/VREF- pins – used when external voltage reference for the ADC module is implemented

Note: The AVDD and AVSS pins must be connected, regardless of ADC use and the ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A value of 0.1 µF (100 nF), 10-20V is recommended. The capacitor should be a low Equivalent Series Resistance (low-ESR) capacitor and have resonance frequency in the range of 20 MHz and higher. It is further recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended that the capacitors be placed on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 µF in parallel with 0.001 µF.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

NOTES:

4.0 MEMORY ORGANIZATION

Note: This data sheet summarizes the features of the PIC32MX1XX/2XX 28/36/44-pin Family of devices. It is not intended to be a comprehensive reference source.For detailed information, refer to **Section 3. "Memory Organization"** (DS60001115), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MX1XX/2XX 28/36/44-pin Family microcontrollers provide 4 GB unified virtual memory address space. All memory regions, including program, data memory, Special Function Registers (SFRs), and Configuration registers, reside in this address space at their respective unique addresses. The program and data memories can be optionally partitioned into user and kernel memories. In addition, the data memory can be made executable, allowing PIC32MX1XX/2XX 28/36/44-pin Family devices to execute from data memory.

Key features include:

- 32-bit native data width
- Separate User (KUSEG) and Kernel (KSEG0/KSEG1) mode address space
- Flexible program Flash memory partitioning
- Flexible data RAM partitioning for data and program space
- Separate boot Flash memory for protected code
- Robust bus exception handling to intercept runaway code
- Simple memory mapping with Fixed Mapping Translation (FMT) unit
- Cacheable (KSEG0) and non-cacheable (KSEG1) address regions

4.1 PIC32MX1XX/2XX 28/36/44-pin Family Memory Layout

PIC32MX1XX/2XX 28/36/44-pin Family microcontrollers implement two address schemes: virtual and physical. All hardware resources, such as program memory, data memory and peripherals, are located at their respective physical addresses. Virtual addresses are exclusively used by the CPU to fetch and execute instructions as well as access peripherals. Physical addresses are used by bus master peripherals, such as DMA and the Flash controller, that access memory independently of the CPU.

The memory maps for the PIC32MX1XX/2XX 28/36/44-pin Family devices are illustrated in Figure 4-1 through Figure 4-6.

Table 4-1 provides SFR memory map details.

NOTES:

REGISTER 9-12: DCHxSSIZ: DMA CHANNEL 'x' SOURCE SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHSSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHSSIZ<15:0>:** Channel Source Size bits

1111111111111111 = 65,535 byte source size
.
.
.
0000000000000010 = 2 byte source size
0000000000000001 = 1 byte source size
0000000000000000 = 65,536 byte source size

REGISTER 9-13: DCHxDSIZ: DMA CHANNEL 'x' DESTINATION SIZE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<15:8>							
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	CHDSIZ<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-0 **CHDSIZ<15:0>:** Channel Destination Size bits

1111111111111111 = 65,535 byte destination size
.
.
.
0000000000000010 = 2 byte destination size
0000000000000001 = 1 byte destination size
0000000000000000 = 65,536 byte destination size

NOTES:

REGISTER 10-11: U1CON: USB CONTROL REGISTER (CONTINUED)

bit 1 **PPBRST:** Ping-Pong Buffers Reset bit
1 = Reset all Even/Odd buffer pointers to the EVEN Buffer Descriptor banks
0 = Even/Odd buffer pointers are not Reset

bit 0 **USBEN:** USB Module Enable bit(4)
1 = USB module and supporting circuitry is enabled
0 = USB module and supporting circuitry is disabled

SOFEN: SOF Enable bit(5)
1 = SOF token is sent every 1 ms
0 = SOF token is disabled

Note 1: Software is required to check this bit before issuing another token command to the U1TOK register (see Register 10-15).

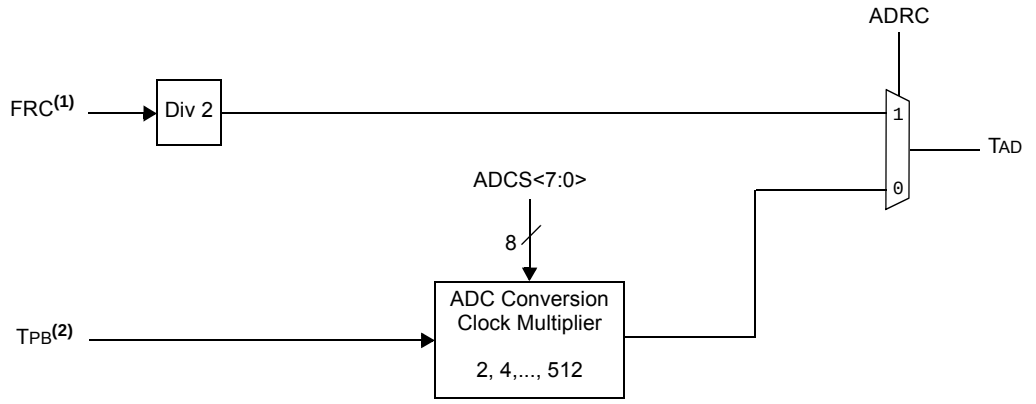
2: All host control logic is reset any time that the value of this bit is toggled.

3: Software must set RESUME for 10 ms if the part is a function, or for 25 ms if the part is a host, and then clear it to enable remote wake-up. In Host mode, the USB module will append a Low-Speed EOP to the RESUME signaling when this bit is cleared.

4: Device mode.

5: Host mode.

FIGURE 22-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: See **Section 30.0 "Electrical Characteristics"** for the exact FRC clock value.

2: Refer to Figure 8-1 in **Section 8.0 "Oscillator Configuration"** for more information.

REGISTER 22-2: AD1CON2: ADC CONTROL REGISTER 2

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	U-0	R/W-0	U-0	U-0
	VCFG<2:0>			OFFCAL	—	CSCNA	—	—
7:0	R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	BUFS	—	SMPI<3:0>				BUFM	ALTS

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-13 **VCFG<2:0>:** Voltage Reference Configuration bits

	VREFH	VREFL
000	AVDD	AVss
001	External VREF+ pin	AVSS
010	AVDD	External VREF- pin
011	External VREF+ pin	External VREF- pin
1xx	AVDD	AVSS

bit 12 **OFFCAL:** Input Offset Calibration Mode Select bit
1 = Enable Offset Calibration mode
Positive and negative inputs of the sample and hold amplifier are connected to VREFL
0 = Disable Offset Calibration mode
The inputs to the sample and hold amplifier are controlled by AD1CHS or AD1CSSL

bit 11 **Unimplemented:** Read as '0'

bit 10 **CSCNA:** Input Scan Select bit
1 = Scan inputs
0 = Do not scan inputs

bit 9-8 **Unimplemented:** Read as '0'

bit 7 **BUFS:** Buffer Fill Status bit
Only valid when BUFM = 1.
1 = ADC is currently filling buffer 0x8-0xF, user should access data in 0x0-0x7
0 = ADC is currently filling buffer 0x0-0x7, user should access data in 0x8-0xF

bit 6 **Unimplemented:** Read as '0'

bit 5-2 **SMPI<3:0>:** Sample/Convert Sequences Per Interrupt Selection bits
1111 = Interrupts at the completion of conversion for each 16th sample/convert sequence
1110 = Interrupts at the completion of conversion for each 15th sample/convert sequence
•
•
•
0001 = Interrupts at the completion of conversion for each 2nd sample/convert sequence
0000 = Interrupts at the completion of conversion for each sample/convert sequence

bit 1 **BUFM:** ADC Result Buffer Mode Select bit
1 = Buffer configured as two 8-word buffers, ADC1BUF7-ADC1BUF0, ADC1BUFF-ADCBUF8
0 = Buffer configured as one 16-word buffer ADC1BUFF-ADC1BUF0

bit 0 **ALTS:** Alternate Input Sample Mode Select bit
1 = Uses Sample A input multiplexer settings for first sample, then alternates between Sample B and Sample A input multiplexer settings for all subsequent samples
0 = Always use Sample A input multiplexer settings

23.1 Comparator Control Registers

TABLE 23-1: COMPARATOR REGISTER MAP

Virtual Address (BF80_#)	Register Name(1)	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
A000	CM1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		00C3
A010	CM2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		00C3
A020	CM3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	COE	CPOL	—	—	—	—	COUT	EVPOL<1:0>		—	CREF	—	—	CCH<1:0>		00C3
A060	CMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	SIDL	—	—	—	—	—	—	—	—	—	—	C3OUT	C2OUT	C1OUT	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 11.2 "CLR, SET and INV Registers"** for more information.

REGISTER 27-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	R/P	R/P
	—	—	—	—	—	—	FWDTWINSZ<1:0>	
23:16	R/P	R/P	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	WINDIS	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:	r = Reserved bit	P = Programmable bit	
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-26 **Reserved:** Write '1'

bit 25-24 **FWDTWINSZ<1:0>:** Watchdog Timer Window Size bits
11 = Window size is 25%
10 = Window size is 37.5%
01 = Window size is 50%
00 = Window size is 75%

bit 23 **FWDTEN:** Watchdog Timer Enable bit
1 = Watchdog Timer is enabled and cannot be disabled by software
0 = Watchdog Timer is not enabled; it can be enabled in software

bit 22 **WINDIS:** Watchdog Timer Window Enable bit
1 = Watchdog Timer is in non-Window mode
0 = Watchdog Timer is in Window mode

bit 21 **Reserved:** Write '1'

bit 20-16 **WDTPS<4:0>:** Watchdog Timer Postscale Select bits
10100 = 1:1048576
10011 = 1:524288
10010 = 1:262144
10001 = 1:131072
10000 = 1:65536
01111 = 1:32768
01110 = 1:16384
01101 = 1:8192
01100 = 1:4096
01011 = 1:2048
01010 = 1:1024
01001 = 1:512
01000 = 1:256
00111 = 1:128
00110 = 1:64
00101 = 1:32
00100 = 1:16
00011 = 1:8
00010 = 1:4
00001 = 1:2
00000 = 1:1
All other combinations not shown result in operation = 10100

Note 1: Do not disable the POSC (POSCMOD = 11) when using this oscillator source.

REGISTER 27-6: DEVID: DEVICE AND REVISION ID REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0>(1)				DEVID<27:24>(1)			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16>(1)							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8>(1)							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0>(1)							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-28 **VER<3:0>:** Revision Identifier bits(1)

bit 27-0 **DEVID<27:0>:** Device ID bits(1)

Note 1: See the *"PIC32 Flash Programming Specification"* (DS60001145) for a list of Revision and Device ID values.

30.1 DC Characteristics

TABLE 30-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range (in Volts)(1)	Temp. Range (in °C)	Max. Frequency
			PIC32MX1XX/2XX 28/36/44-pin Family
DC5	2.3-3.6V	-40°C to +85°C	40 MHz
DC5b	2.3-3.6V	-40°C to +105°C	40 MHz

Note 1: Overall functional device operation at VBORMIN < VDD < VDDMIN is tested, but not characterized. All device Analog modules, such as ADC, etc., will function, but with degraded performance below VDDMIN. Refer to parameter BO10 in Table 30-11 for BOR values.

TABLE 30-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD – S IOH) I/O Pin Power Dissipation: I/O = S (({VDD – VOH} x IOH) + S (VOL x IOL))	PD	PINT + PI/O			W
Maximum Allowed Power Dissipation	PDMAX	(TJ – TA)/θJA			W

TABLE 30-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 28-pin SSOP	θJA	71	—	°C/W	**1**
Package Thermal Resistance, 28-pin SOIC	θJA	50	—	°C/W	**1**
Package Thermal Resistance, 28-pin SPDIP	θJA	42	—	°C/W	**1**
Package Thermal Resistance, 28-pin QFN	θJA	35	—	°C/W	**1**
Package Thermal Resistance, 36-pin VTLA	θJA	31	—	°C/W	**1**
Package Thermal Resistance, 44-pin QFN	θJA	32	—	°C/W	**1**
Package Thermal Resistance, 44-pin TQFP	θJA	45	—	°C/W	**1**
Package Thermal Resistance, 44-pin VTLA	θJA	30	—	°C/W	**1**

Note 1: Junction to ambient thermal resistance, Theta-JA (θJA) numbers are achieved by package simulations.

TABLE 30-14: COMPARATOR VOLTAGE REFERENCE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
D312	TSET	Internal 4-bit DAC Comparator Reference Settling time	—	—	10	µs	See **Note 1**
D313	DACREFH	CVREF Input Voltage Reference Range	AVSS	—	AVDD	V	CVRSRC with CVRSS = 0
			VREF-	—	VREF+	V	CVRSRC with CVRSS = 1
D314	DVREF	CVREF Programmable Output Range	0	—	0.625 x DACREFH	V	0 to 0.625 DACREFH with DACREFH/24 step size
			0.25 x DACREFH	—	0.719 x DACREFH	V	0.25 x DACREFH to 0.719 DACREFH with DACREFH/32 step size
D315	DACRES	Resolution	—	—	DACREFH/24	—	CVRCON<CVRR> = 1
			—	—	DACREFH/32	—	CVRCON<CVRR> = 0
D316	DACACC	Absolute Accuracy(2)	—	—	1/4	LSB	DACREFH/24, CVRCON<CVRR> = 1
			—	—	1/2	LSB	DACREFH/32, CVRCON<CVRR> = 0

Note 1: Settling time was measured while CVRR = 1 and CVR<3:0> transitions from '0000' to '1111'. This parameter is characterized, but is not tested in manufacturing.

2: These parameters are characterized but not tested.

TABLE 30-15: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Comments**
D321	CEFC	External Filter Capacitor Value	8	10	—	µF	Capacitor must be low series resistance (1 ohm). Typical voltage on the VCAP pin is 1.8V.

TABLE 30-34: ADC MODULE SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions (see Note 5): 2.5V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
ADC Accuracy – Measurements with Internal VREF+/VREF-							
AD20d	Nr	Resolution	10 data bits			bits	**(Note 3)**
AD21d	INL	Integral Non-linearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD22d	DNL	Differential Non-linearity	> -1	—	< 1	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Notes 2,3)**
AD23d	GERR	Gain Error	> -4	—	< 4	LSb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD24d	EOFF	Offset Error	> -2	—	< 2	Lsb	VINL = AVSS = 0V, AVDD = 2.5V to 3.6V **(Note 3)**
AD25d	—	Monotonicity	—	—	—	—	Guaranteed
Dynamic Performance							
AD32b	SINAD	Signal to Noise and Distortion	55	58.5	—	dB	**(Notes 3,4)**
AD34b	ENOB	Effective Number of bits	9.0	9.5	—	bits	**(Notes 3,4)**

Note 1: These parameters are not characterized or tested in manufacturing.

2: With no missing codes.

3: These parameters are characterized, but not tested in manufacturing.

4: Characterized with a 1 kHz sine wave.

5: The ADC module is functional at VBORMIN < VDD < 2.5V, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

TABLE 31-5: EXTERNAL CLOCK TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
MOS10	FOSC	External CLKI Frequency (External clocks allowed only in EC and ECPLL modes)	DC 4	— —	50 50	MHz MHz	EC **(Note 2)** ECPLL **(Note 1)**

Note 1: PLL input requirements: 4 MHz ≤ FPLLIN ≤ 5 MHz (use PLL prescaler to reduce Fosc). This parameter is characterized, but tested at 10 MHz only at manufacturing.

2: This parameter is characterized, but not tested in manufacturing.

TABLE 31-6: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
MSP10	TscL	SCKx Output Low Time **(Note 1,2)**	TSCK/2	—	—	ns	—
MSP11	TscH	SCKx Output High Time **(Note 1,2)**	TSCK/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

TABLE 31-7: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typ.**	**Max.**	**Units**	**Conditions**
MSP10	TscL	SCKx Output Low Time **(Note 1,2)**	TSCK/2	—	—	ns	—
MSP11	TscH	SCKx Output High Time **(Note 1,2)**	TSCK/2	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

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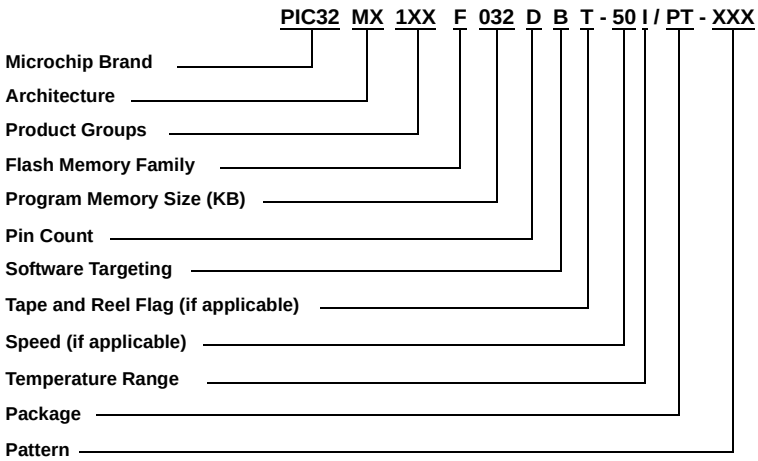
PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.



Example:

PIC32MX110F032DT-I/PT:
General purpose PIC32,
32-bit RISC MCU with M4K® core,
32 KB program memory, 44-pin,
Industrial temperature,
TQFP package.

Flash Memory Family

Architecture	MX	= M4K® MCU core
Product Groups	1XX	= General purpose microcontroller family
	2XX	= General purpose microcontroller family
Flash Memory Family	F	= Flash program memory
Program Memory Size	016	= 16K
	032	= 32K
	064	= 64K
	128	= 128K
	256	= 256K
Pin Count	B	= 28-pin
	C	= 36-pin
	D	= 44-pin
Software Targeting	B	= Targeted for Bluetooth® Audio Break-in devices
Speed	( )	= 40 MHz – ( ) indicates a blank field; package markings for 40 MHz devices do not include the Speed
	50	= 50 MHz
Temperature Range	I	= -40°C to +85°C (Industrial)
	V	= -40°C to +105°C (V-temp)
Package	ML	= 28-Lead (6x6 mm) QFN (Plastic Quad Flatpack)
	ML	= 44-Lead (8x8 mm) QFN (Plastic Quad Flatpack)
	PT	= 44-Lead (10x10x1 mm) TQFP (Plastic Thin Quad Flatpack)
	SO	= 28-Lead (7.50 mm) SOIC (Plastic Small Outline)
	SP	= 28-Lead (300 mil) SPDIP (Skinny Plastic Dual In-line)
	SS	= 28-Lead (5.30 mm) SSOP (Plastic Shrink Small Outline)
	TL	= 36-Lead (5x5 mm) VTLA (Very Thin Leadless Array)
	TL	= 44-Lead (6x6 mm) VTLA (Very Thin Leadless Array)
Pattern		Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise)
	ES	= Engineering Sample